



Selective Soldering System GoSELECTIVE

Maximum Performance at Minimum Cost

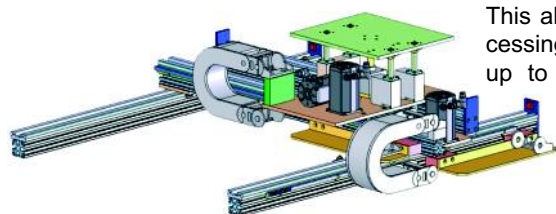
- High-precision selective miniwave soldering system for stand-alone operation.
- Manual infeed and outfeed of the assemblies.
- Precise axis system for exact positioning of the various working stations.
- Highest flexibility due to quickly exchangeable solder nozzles.
- Automatic wave height control and solder level control provide maximum process reliability.
- Nitrogen inertion of the solder wave ensures highest soldering quality.
- For assemblies up to 500 x 500 mm [19.68 x 19.68 inch].

Maximum performance in selective soldering at minimum cost: this is the GoSELECTIVE from SEHO.

The GoSELECTIVE offers an uncompromisingly high soldering quality and maximum flexibility particularly for small and medium-sized production volumes. The high-grade and compact machine concept "Made in Germany" ensures absolutely reproducible soldering results at simultaneously small footprint and thus offers an economic alternative to traditional hand soldering processes.

The Concept: Flexible and High-Precise

The GoSELECTIVE is designed for stand-alone operation. Infeed and outfeed of the assemblies is made manually. During the process the assembly remains on its position whereas the working stations, which are mounted on a high-precision axis system, successively approach the solder joints.



This allows flexible processing of assemblies up to 500 x 500 mm [19.68 x 19.68"] with absolutely reproducible results.

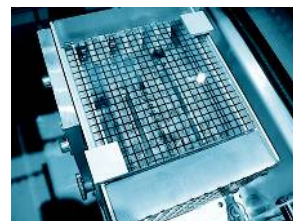
Of course, the GoSELECTIVE is ideally suited for both, lead-free and lead containing production processes.

Process Stations: High Soldering Quality Guaranteed

The GoSELECTIVE is featured with a micro drop jet fluxer which ensures an exact flux apply to the point, with a precisely defined quantity of one drop. This allows a defined spray pattern with minimum overspray. Therefore, surrounding areas and components which are not meant to be soldered, will not be contaminated. The system allows the processing of all usual flux types up to a solid content of 5 %.



The preheating area is provided with halogen emitters which ideally support the evaporation of the solvent and preheating of the printed circuit boards.



The soldering unit is designed for miniwave soldering processes and therefore ensures highest flexibility in your production. A variety of quickly exchangeable solder nozzles, suitable for dip and drag soldering processes, is available.

The solder nozzle technology of the GoSELECTIVE permits very small distances between the solder joints, thus it is possible to also precisely solder points which generally are difficult to get to.

A local nitrogen inertion ensures an oxide-free solder wave and thus ideal flow properties of the solder. Moreover, this guarantees minimum maintenance requirements.



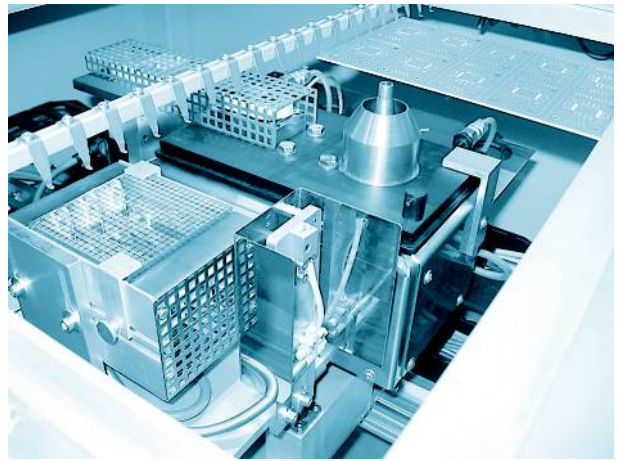
Highest process reliability is ensured with an automatic solder wave monitoring and wave height control as well as a solder level control.

The Software: Easy and Comfortable

The GoSelective is featured with an up-to-date control unit. The system provides an SPS as well as a high-precision axis control.

Operation of the machine is made via a coloured 10" touch display.

Teaching is particularly easy. Only the x and y coordinates of the components to be soldered have to be entered and filed with the soldering program. Of course, all soldering programs can be saved and protected via password.



Equipment Features

Fluxer

micro drop jet fluxer	●
wetting width on PCB	approx. 1 mm
automatic level control with capacitive sensor	●

Preheating

halogen emitters	○
active area	100 x 100 mm [3.94 x 3.94 inch]

Soldering Unit for Miniwave Soldering Processes

solder pot suited for lead-free solder alloys	●
quickly exchangeable solder nozzles	○
nitrogen operation	●
automatic wave height control	●
automatic solder level control	●

Control Unit

touch screen display with comfortable user interface	●
display of status and maintenance messages	●
password protection	●
Offline Teach Programm (available in November 2007)	○

Handling of Assemblies

infeed and outfeed of assemblies	manually
max. board dimensions	500 x 500 mm [19.68 x 19.68 inch]

further options upon request ● Standard ○ Option

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